



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

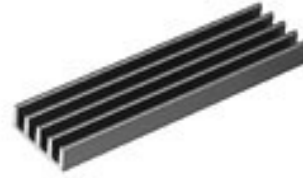


Board Level Cooling – Extruded 5080



BOARD LEVEL COOLING – Extruded 5080

Extruded 5080 is a series of rectangular bi-directional board level heat sinks designed to cool DIP 24 and DIP 40 devices. Representative image only.



ORDERING INFORMATION

Part Number	Device Type
508500B00000G	DIP 24
508700B00000G	DIP 40

HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Epoxy
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	13.46
Heat Sink Length (mm)	See "A" Dim below
Heat Sink Height (mm)	4.83
Heat Sink Mounting Direction	Horizontal

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

Part Number	"A" Dim
508500B00000G	31.75
508700B00000G	50.80

